

**ANX3133F**
*No Clean Liquid Flux*

**Product Description**

Hasaconi ANX3133F is a no clean flux and with very low solid content. This flux offers excellent cleanliness and aesthetic values on PCB surface and solder joints. With very low residue left after soldering, this makes it most suitable for automatic inspection by a checker pin in the production line. ANX3133F delivers excellent solderability which eliminates many defects, such as bridging, icicles and non-wetting in soldering. Besides, it also shows good wicking effect in through-hole filling.

**Application**

ANX3133F is specially formulated for foaming as well as brushing and dipping process. Recommended onboard preheat temperature is 80 – 100 °C.

**Residue Removal**

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

**Recommended Solvent**

Asahi's complementary Solvent #2000. Solvent can be stored for about 2 year under normal storage conditions of 25°C.

**Health and Safety**

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

**Storage**

Under proper storage conditions, ANX3133F can be stored for up to 6 months. ANX3133F is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

**Packaging**

Available in 18kg/carboy.

**Specification**

Item	Result
State	Liquid
Colour	Colourless
Specific Gravity @ 25°C	0.790 +/- 0.005
JIS Z 3197 8.2.2	
Non-volatile Solid Content (110°C, 1hr)	1.7 +/- 0.2 wt%
IPC-TM-650 2.3.34	
JIS Z 3197 8.1.3	
Halide Content	0.08 +/- 0.01 wt%
JIS Z 3197 8.1.4.2.1	
Acid Value Test	12.0 +/- 1 mg KOH/g flux
IPC-TM-650 2.3.13	
JIS Z 3197 8.1.4.1	
Water Extract Resistivity	> 1 x 10 <sup>4</sup> Ω-cm
JIS Z 3197 8.1.1	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	> 1 x 10 <sup>8</sup> Ω, Pass
IPC-TM-650 2.6.3.3	
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
IPC-TM-650 2.6.14.1	
Copper Corrosion Test	Pass
IPC-TM-650 2.6.15	
JIS Z 3197 8.4.1	
Copper Mirror Test	Classified as "M", Pass
IPC-TM-650 2.3.32	
JIS Z 3197 8.4.2	
Flux Activity Classification	ROM1
IPC J-STD-004	
Spread Factor	> 85% (SnPb)
JIS Z 3197 8.3.1.1	
Residue Dryness Test	Dry
IPC-TM-650 2.4.47	
JIS Z 3197 8.5.1	
Surface Finish	Shiny

**DISCLAIMER OF LIABILITY**

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